



Regionální centrum
speciální optiky
a optoelektronických
systémů

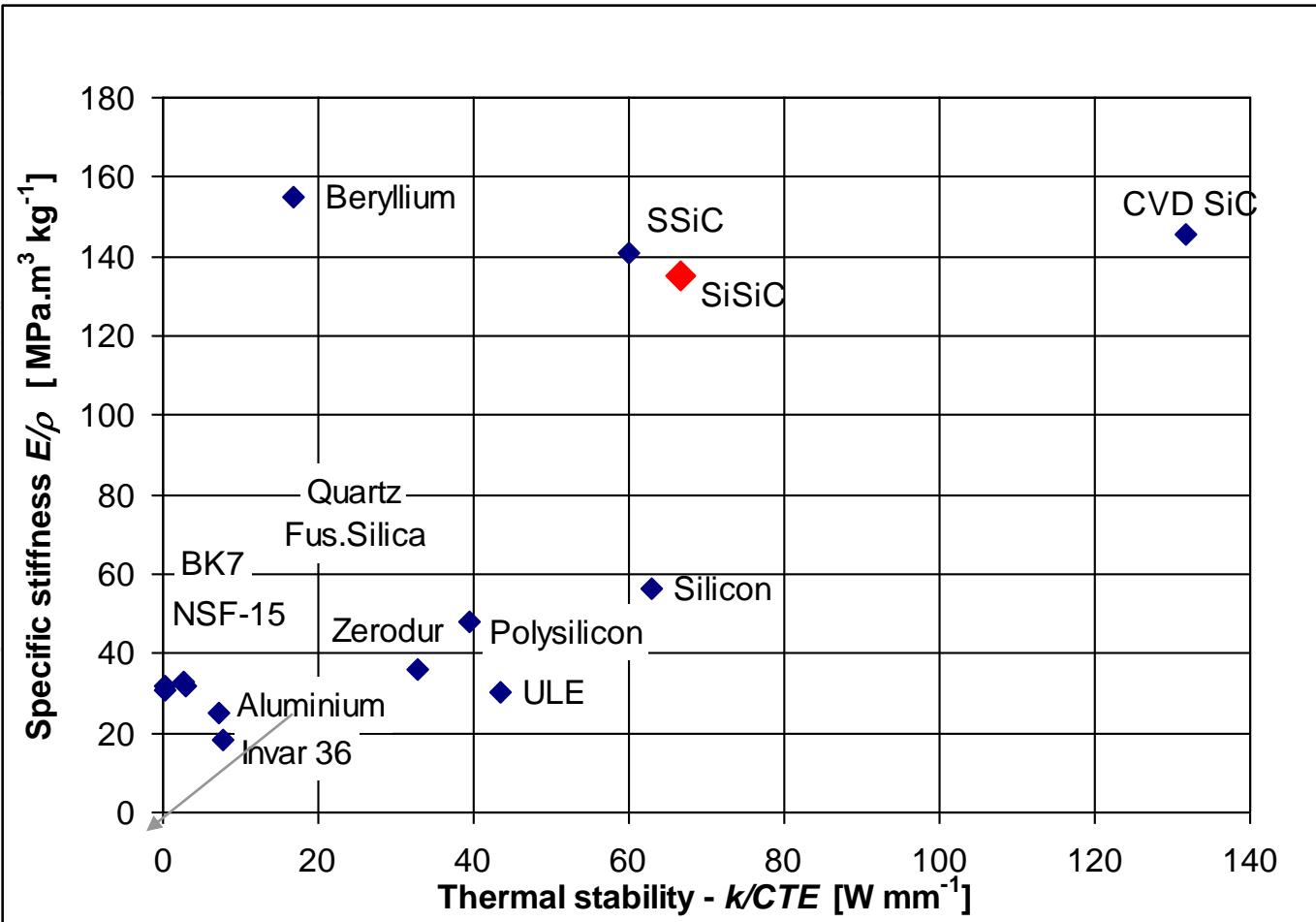
Research Centre for
Special Optics and
Optoelectronic
Systems

toptec@ipp.cas.cz
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METIS coronagraph

Progress on mirrors M1 and M2

Selection of the material



SiSiC – hard material needs special technology for cutting and grinding

Material properties

SiSiC

- Youngs modulus = 380MPa
- Poissons constant = 0.17
- Density = 3.07 g cm⁻³
- Bending strength = 340MPa

ZERODUR

- Youngs modulus = 90MPa
- Poissons constant = 0.24
- Density = 2.53 g cm⁻³
- Bending strength = 109MPa

NSF-15

- Youngs modulus = 90MPa
- Poissons constant = 0.24
- Density = 2.92 g cm⁻³
- Bending strength = 20MPa?

How to manufacture

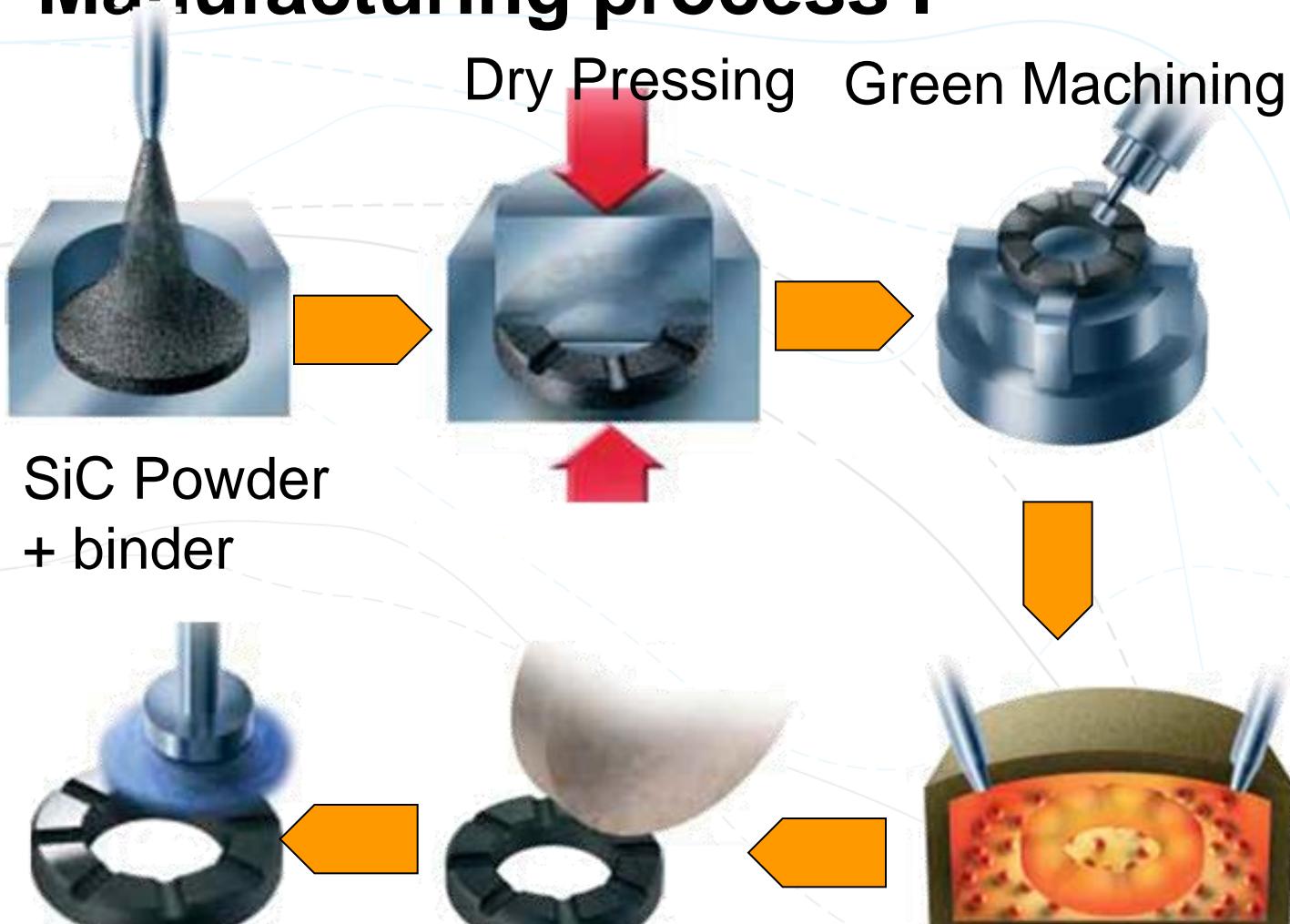
- Silicon-infiltrated silicon carbide
(SiSiC) - substrate
 - + Si coating (self organized structure)

20 μ layer
for ion-beam figuring/polishing

Manufacturing process I

Dry Pressing

Green Machining

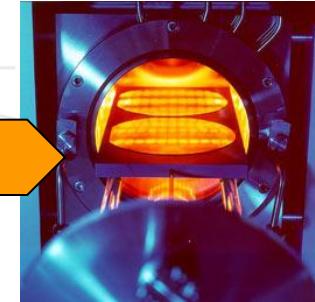


Manufacturing process II

CMP Polishing
(100Å; $\lambda/10$)



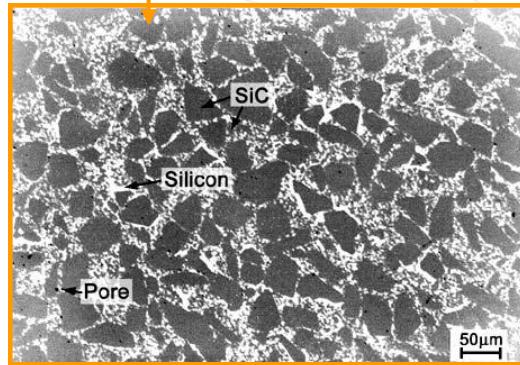
CVD of Si



Superpolishing

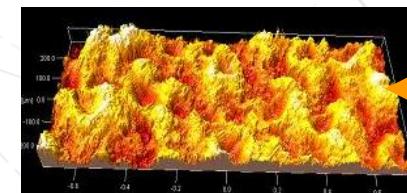


$\approx 10-20 \mu$



Sufficient for most of
applications
But not for UV and EUV

Measurement



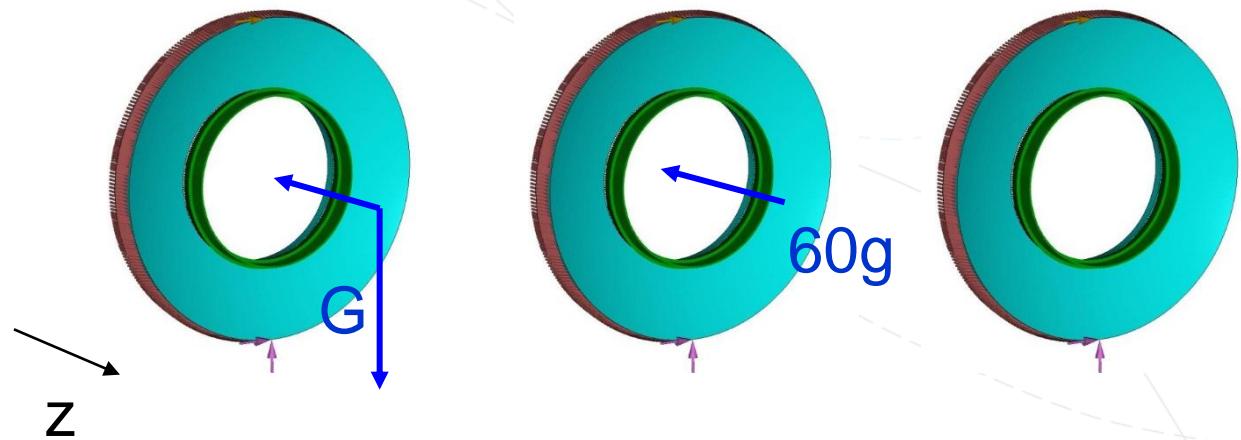
Goal of 2Å
microroughness

Numerical Tests - parameters

- FEM –Abaqus, MSC.Nastran
- Topology optimization – ATOM (Dassault Systèmes)
- Structured hexahedral mesh (60 000 elements)
- Linear material model, model (E , flexular strength) for SiSiC validated by banding test

Numerical Tests

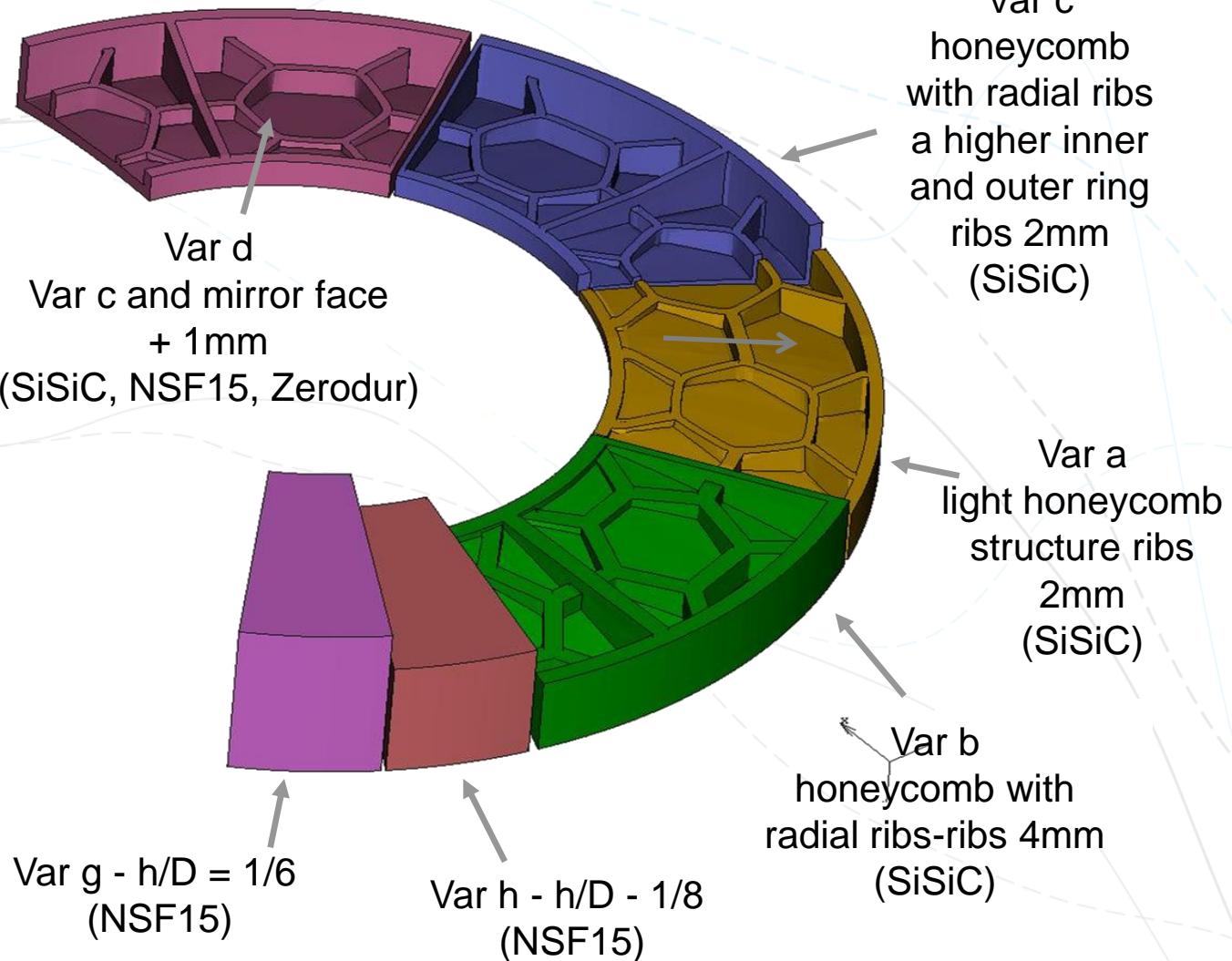
1. Modal analysis
2. Deformation of the mirror under its own weight (axial and vertical load)
3. Shock load 60g
4. Stiffness (perpendicular to mirror plane)
5. Random load, sine load, shock load



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Variants – design + material



Results

Var.	Design	Material	Mass	1st Eigenfrq.	Loadcase 1		Loadcase 2		Loadcase 3	Loadcase 4	
					g_y	g_z	Displacement z	Max. Eq. Stress	Stiffness	Stiffness/ Mass	
			[g]	[Hz]	[nm]	[nm]	[nm]	[MPa]	[kN mm ⁻¹]	[N (mm g) ⁻¹]	
a	D1	SiSiC	340	950	69	42	1.8	24	71		
b	D2	SiSiC	520	1 384	51	43	2.3	33	64		
c	D3	SiSiC	420	1 295	49	35	2.5	50	119		
d	D4	SiSiC	520	1 378	43	35	2.6	51	98		
e	D4	Zerodur	429	742	145	121	1.9	12	28		
f	D4	NSF-15	495	688	173	143	2.2	12	24		
g	1/6	NSF-15	3 003	2 080	83	46	0.8	255	85		
h	1/8	NSF-15	2 057	1 493	123	83	1.4	93	45		

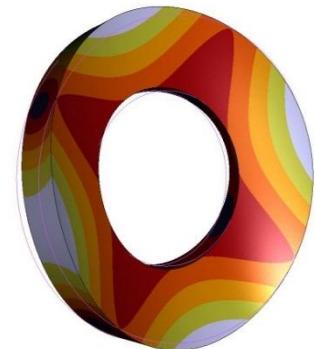
Results LC 1 and 2

Loadcase 1

Var d



Var g

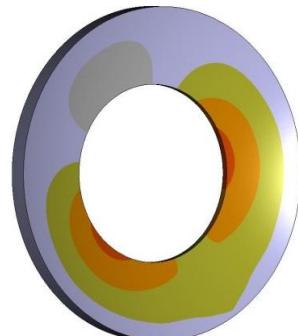


1378Hz

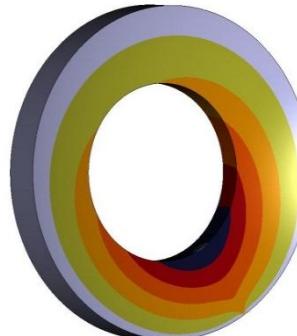
2080Hz

Loadcase 2 – Gy

Var d

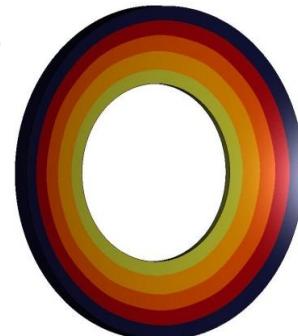


Var g

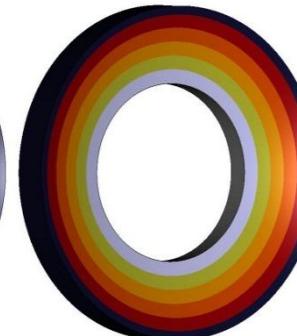


Loadcase 2 – Gz

Var d



Var g



-82nm

displacement z

5nm

0nm

displacement z

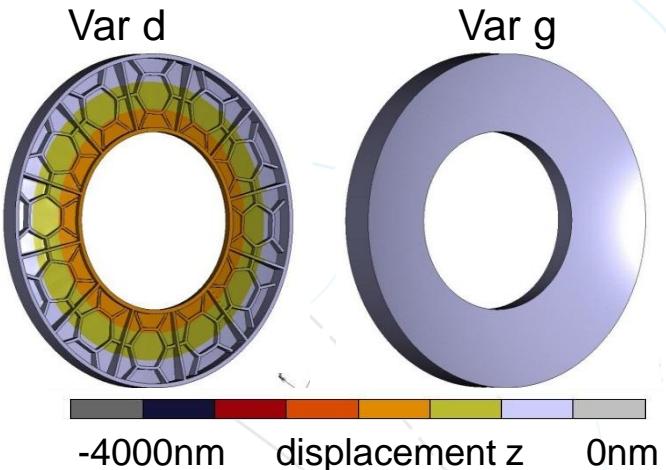
46nm

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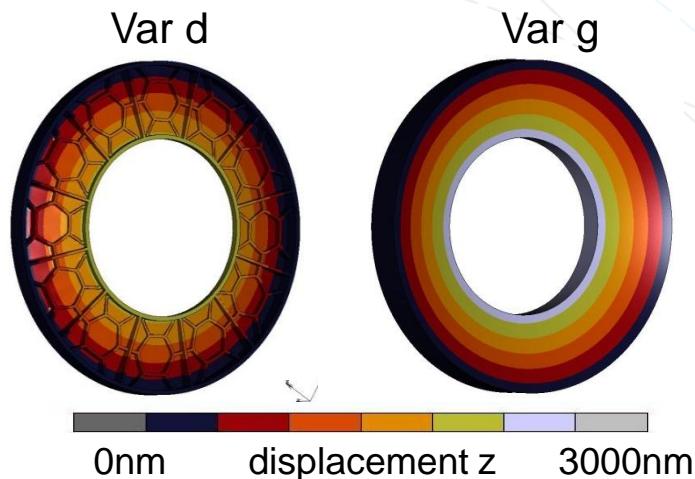
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Results LC 3 and 4

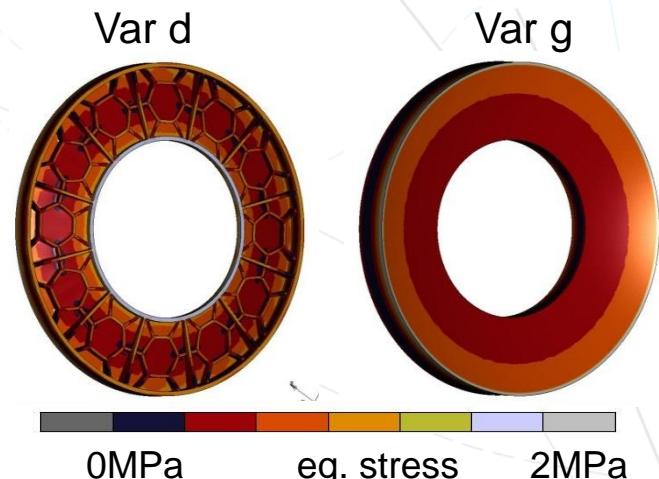
Loadcase 4



Loadcase 3

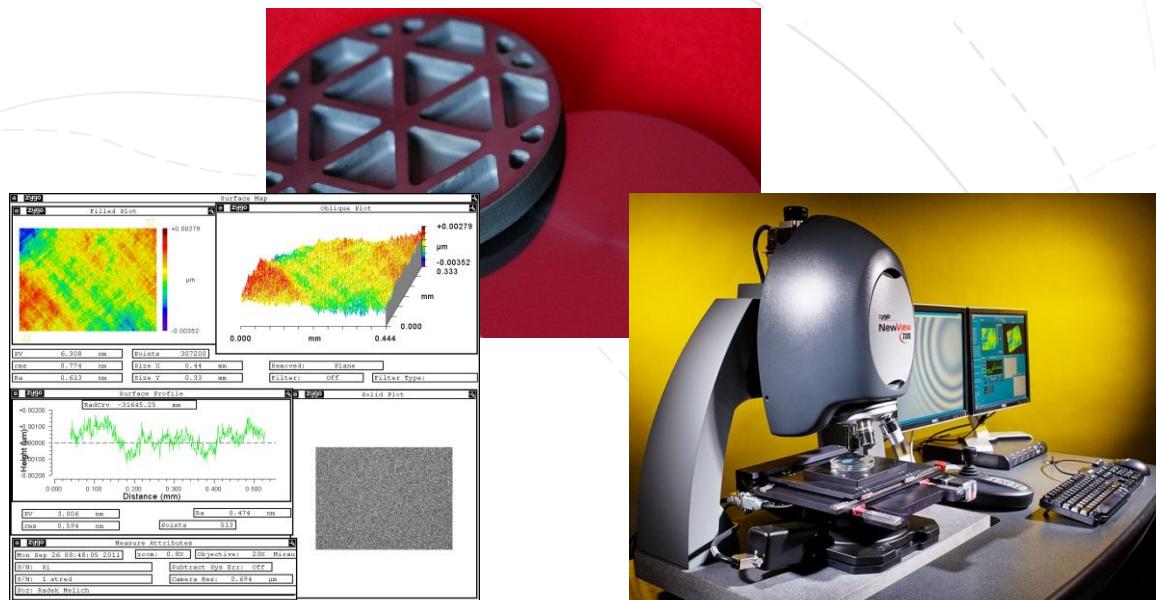


Loadcase 3



M1 and M2 baseplates

- Grining and polishing tests on SiSiC sample baseplates
- Polishing test (not IBF) on amorphous Si block proved 6 Å microroughness





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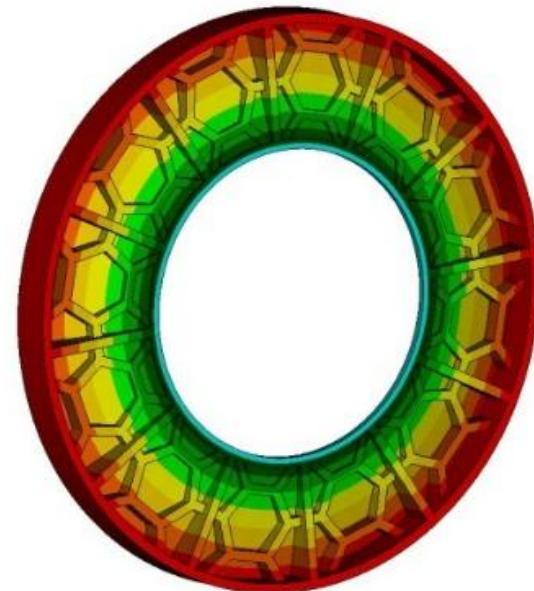
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M1 and M2 baseplates II

Currently we have ordered 1:1 scale sample
base-plates which are being produced by
CERAMTECH (USA, CZ)

C/D phases
final tests &
manufacturing



Polishing test

We are ready for polishing tests on 1:1 scale samples:

- Polishing of the substrate
- Si layer CVD (chemical vapour deposition) on a baseplate
- polishing of the Si layer
- IBF (Ion beam finishing) to reach the required microroughness

ESA-PRODEX contracts

Czech contribution to METIS is covered by PRODEX (fully confirmed)

- Czech PRODEX confirmed the phase B in June 2010, including the budget
- since then no action at ESTEC office !
- negotiations with ESA-PRODEX office only since June 2012
- electronic version of signed contract delivered to TOPTEC on 29/11/2012
- Czech PRODEX confirmed the phase C/D in 2012
- Negotiations with ESA-PRODEX office to prepare contract with TOPTEC